

Heterogeneous Integration Roadmap (HIR) Workshop

EPTC 2018

December 6th - 1:50 pm to 5 pm

Welcome to the Heterogeneous Integration Roadmap Workshop hosted by the 2018 EPTC Conference.

Our Industry has reinvented itself through multiple disruptive changes in technologies, products and markets.. With the rapid migration of logic, memory and applications to the Cloud infrastructures, Data Centers and 5G Networks, the Internet of Things (IoT) to internet of everything (IOE), Autonomous Vehicles, the proliferation of Smart Devices every where, and increasing interest in artificial intelligence (AI) & Virtual Reality (VR) , the pace of innovation is increasing to meet these challenges. What are the paths forward?

The IEEE Heterogeneous Integration Technology Roadmap (HIR), is sponsored by the IEEE Electronic Packaging Society (EPS), the Electron Devices Society (EDS), Photonics Society together with ASME EPPD and SEMI. It will address the future directions of heterogeneous integration technologies and applications serving future markets and applications, so very crucial to our profession, our industries, academic and research communities. Following the spirit of ITRS, the HIR is a pre-competitive technology roadmap provides long-term vision to identify the needs of future technology challenges, roadblocks, and potential solutions focused on system integration and broad market applications in order to accelerate progress for the broad electronics industry.



Workshop Agenda

In this workshop we shall feature an introduction of the HIR followed by presentations from 5 of the 22 technical working groups (TWG)

- Introduction Andrew Tay
- Heterogeneous Integration Roadmap Overview Bill Chen
- Wafer Level Packaging (WLP) Rozalia Beica
- Thermal Management (invited)
- System in Package (SiP) Rolf Aschenbrenner
- Electronics & Photonics Integration Bill Bottoms
- Design & Simulation Christopher Bailey
- Wrap-Up Bill Bottoms & Bill Chen

The Conference room will be available for further informal dialog & discussion until 6:30 pm